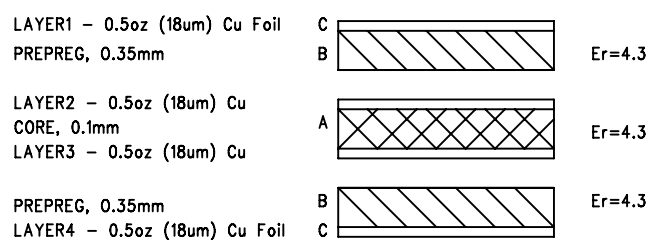


PB000510D-G PCB STACK-UP STRUCTURE



FINISH BOARD THICKNESS: 0.8mm +/-0.1mm

MATERIALS AND SPECIFICATIONS

- A. BASE MATERIAL - 0.5oz (18um) Cu CLAD DOUBLE SIDED LAMINATE,
FR4 TO IPC-4101/24 (MINIMUM Td 330 DEGREES C, SUITABLE FOR THE LEAD FREE PROCESS).
- B. PRE PREG MATERIAL SELECTED TO MATCH THE ABOVE LAMINATE,
PRE PREG TO IPC-4101/24 (MINIMUM Td 330 DEGREES C, SUITABLE FOR THE LEAD FREE PROCESS).
2 SHEETS MINIMUM BETWEEN BONDING LAYERS.
GLASS STYLE, RESIN FLOW AND GEL TIMES ARE OPTIONAL.
- C. Cu FOIL OUTER LAYERS TO IPC-MF-150/3.